



EXPRESS MAIL LABEL NO. ER 003068951 US
Date of Deposit 2/23/04
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Appn. Ser. No Not Yet Ass'd : Art Unit Not Yet Ass'd
Filed Herewith : Examiner Not Yet Ass'd
Inventors L.S. Mokl : Atty. Dkt. No. YOR920030206US1

For: HEAT DISSIPATION INTERFACE FOR
SEMICONDUCTOR CHIP STRUCTURES

PATENT APPLICATION TRANSMITTAL LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, Va. 22313 - 1450
Sir:

Transmitted herewith for filing is a Patent Application including:

Request and Transmittal Letter - 1 page
Patent Specification, Claims & Abstract - 12 pages
Informal Drawings - 6 sheets
Declaration - 3 pages
Assignment + cover - 3 pages
Deposit Acct. Authorizations for Filing Fee and for As'mt recordation fee.
Information Disclosure Transmittal plus references

The filing fee has been calculated as shown below:

Basic Fee	\$770.00
Total claims 9 - 20 = 0 extra	00.00
Independent claims 2 - 3 = 0 extra	00.00
Filing fee Total	\$770.00

The assignment recordation fee of \$40.00

Deposit account authorizations for \$770.00 and \$ 40.00 are included

Respectfully submitted,

by *Alvin J. Riddles* 2/23/04

Alvin J. Riddles
Reg.No. 17862

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EXPRESS MAIL CERTIFICATE

Commissioner for Patents
P.O. Box 1450
Alexandria, Va. 22313 – 1450
Sir:

EXPRESS MAIL LABEL NO. ER 003068951 US

Date of Deposit 02/23/04

I hereby certify that the following attached paper or fee

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being deposited with the United States Postal Service "Express Mail Post Office to
Addressee" service under 37CFR 1.10 on the date indicated above and is addressed to

Commissioner for Patents

P.O. Box 1450

Alexandria, Va. 22313 – 1450

by

Alvin J. Riddles

Typed or Printed Name of person mailing paper or fee

Alvin J. Riddles 2/23/04

Signature and date of person mailing paper or fee

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Commissioner for Patents
P.O. Box 1450
Alexandria, Va. 22313 - 1450
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DEPOSIT ACCOUNT CHARGE AUTHORIZATION LETTER

For the Filing Fee for the above identified application
a charge authorization estimated to be \$770.00 on Deposit Account 50-0510 is provided
herewith.

Respectfully submitted,

by  2/23/04

Alvin J. Riddles
Reg.No. 17862

Dkt. No. YOR920030206US1

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Filed Herewith : Examiner Not Yet Ass'd
Inventors L.S. Mokl : Atty. Dkt. No. YOR920030206US1


For: HEAT DISSIPATION INTERFACE FOR
SEMICONDUCTOR CHIP STRUCTURES

Commissioner for Patents
P.O. Box 1450
Alexandria, Va. 22313 – 1450
Sir:

DEPOSIT ACCOUNT CHARGE AUTHORIZATION LETTER

For the Assignment Recordation Fee for the above identified application a charge authorization of \$ 40.00 on Deposit Account 50-0510 is provided herewith.

Respectfully submitted,

by  2/23/04
Alvin J. Riddles
Reg.No. 17862

Dkt. No. YOR920030206US1